A Leading Provider of Microcontrollers & Analog Semiconductors

Date: 08 Apr 2013

Product Category: Memory

Device Family:

Notification subject: CCB 1223 Initial Notice: Qualification 24xx1025 and 24xx1026 device families in 8L SOIJ package at MTAI assembly site.

Notification text:

PCN Status:
Initial notification

Microchip Parts Affected:
See attachments of affected catalog part numbers (CPN) labeled as…
PCN_CYER-02KOZN657_Affected_CPN.xls
PCN_CYER-02KOZN657_Affected_CPN.pdf

Description of Change:
Qualification 24xx1025 and 24xx1026 device families in 8L SOIJ package at MTAI assembly site.

Impacts to Data Sheet:
None

Reason for Change:
To improve manufacturability

Change Implementation Status:
In Progress

Estimated First Ship Date:
May 30, 2013 (date code: 1322)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Markings to Distinguish Revised from Unrevised Devices:
Traceability code

Revision History:
April 8, 2013: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable

products.

Attachment(s): PCN_CYER-02KOZN657_Affected CPN.xls PCN_CYER-02KOZN657_Affected CPN.pdf PCN_ CYER-02KOZN657_Qual Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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To opt out of future offer or information emails (other than product change notification emails), click here to go to microchipDIRECT and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

Product Change Notification - CYER-02KOZN657

Parts Affected

24AA1025
24AA1026
24FC1025
24FC1026
24LC1025
24LC1026

PCN_CYER-02KOZN657
CATALOG_PART_NBR
24AA1025-I/SN
24AA1025T-I/SN
24AA1025T-I/SNVAO
24FC1025-I/SN
24FC1025T-I/SN
24LC1025-E/SN
24LC1025-E/SN16KV01
24LC1025-I/SN
24LC1025T-E/SN
24LC1025T-E/SN16KVAO
24LC1025T-I/SN
24AA1026-I/SN
24AA1026T-I/SN
24FC1026-I/SN
24FC1026T-I/SN
24LC1026-E/SN
24LC1026-I/SN
24LC1026T-E/SN
24LC1026T-I/SN

QUALIFICATION PLAN

PCN #: CYER-02KOZN657

Date:
Mar 27, 2013

Qualification 24xx1025 and 24xx1026 device families in 8L SOIJ package at MTAI assembly site.

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Purpose:________________ Qualification 24xx1025 and 24xx1026 device families in 8L SOIJ package at MTAI assembly site.

MP code:________________ 36010

Part No.: ________________ 24AA1025

BD No:__________________ BDM-000312 rev. B

CCB No: ________________ 1223

Package:

Type ___________________ 8L SOIC

Width or Size ____________ 150 mils

Die thickness: ___________ Top: 6 mils, Spacer: 6 mils, Bottom: 6 mils

Die size: ________________ Top/Bottom (DEDX2) 111.0 x 78.7 mils, Spacer 47 x 89 mils

Lead frame:

Paddle size: _____________ 95 x 130

Material_________________ A194

Surface_________________ Ag plate

Process ________________ Stamp

Lead Lock ______________ No

Part Number_____________ 10100809

Wire:

Material_________________ Au

Die Attach Epoxy:

Part Number_____________ Top/Bottom: 8390A, Spacer: 8006NS

Conductive______________ Top/Bottom: Yes, Spacer: No

Mold Compound: __________ G600V

Reliability Test plan: ______ See attached, STD Package Reliability Test plan on each package.

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5	30 bonds from a minimum of 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5	0	5	30 bonds from a minimum of 5 devices.
Wire Sweep								Required for any reduction in wire bond thickness.
Lead Integrity	JESD22 B105	5	0	1	5	0 (No lead breakage or cracks)	5	10 leads from each of 5 parts. Not required for SMD, only required for through-hole.
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	
HTSL (High Temp Storage Life)	+175 C for 504 hours or 150°C for 1008 hrs. Electrical test pre and post stress at +25C and hot temp. pre/post test 1 lot at 85°C and 125°C	45	5	1	50	0	10	
Preconditioning - Required for surface mount devices	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020C for package type; Electrical test pre and post stress at +25°C. Perform SAM analysis using the standard sample size. MSL-1 @ 260°C	231	15	3	738	0	15	Spares should be properly identified. 77 parts from each lot to be used for HAST, Autoclave, Temp Cycle test.
HAST	+130°C/85% RH for 96 hours. Electrical test pre and post stress at +25°C and hot temp. pre/post test 1 lot at 85°C and 125°C	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Unbiased HAST	+130°C/85% RH for 96 hrs or +110°C/85% RH for 264 hrs	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
Temp Cycle	-65°C to +150°C for 500 cycles. Electrical test pre and post stress at hot temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress. pre/post test 1 lot at 85°C and 125°C	77	5	3	246	0	15	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.